

FIG. 1

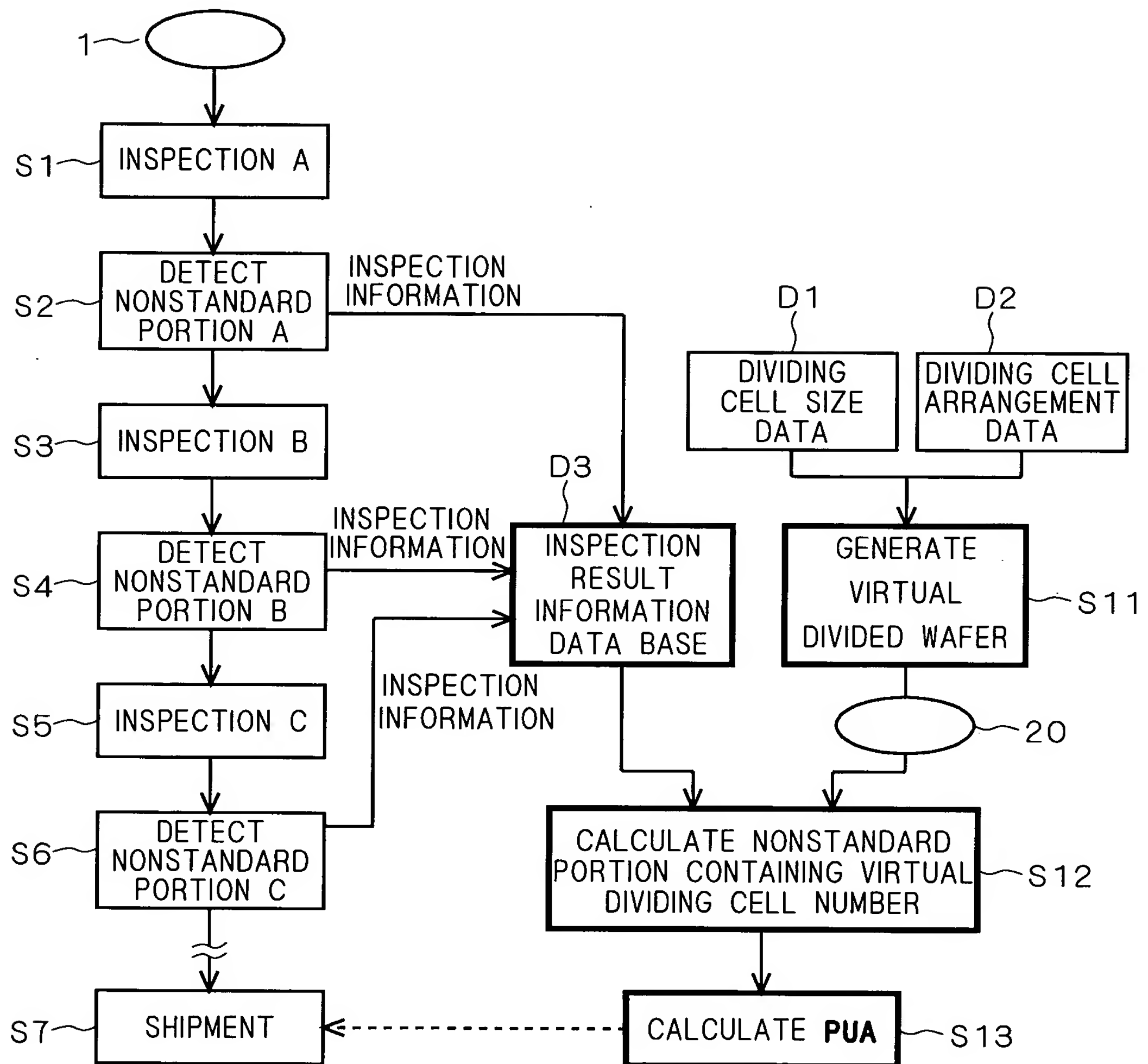


FIG. 2

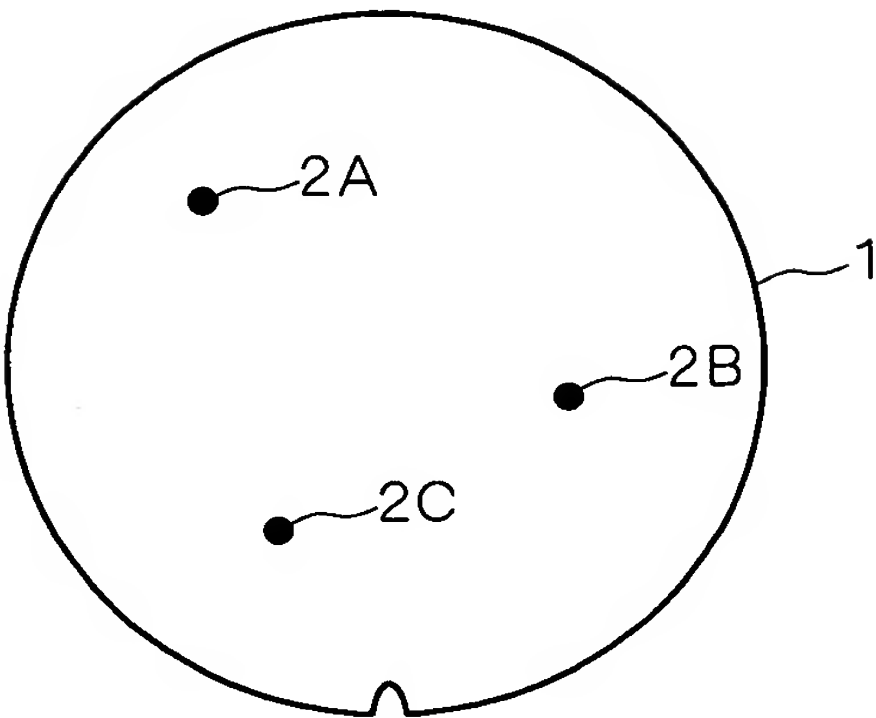


FIG. 3

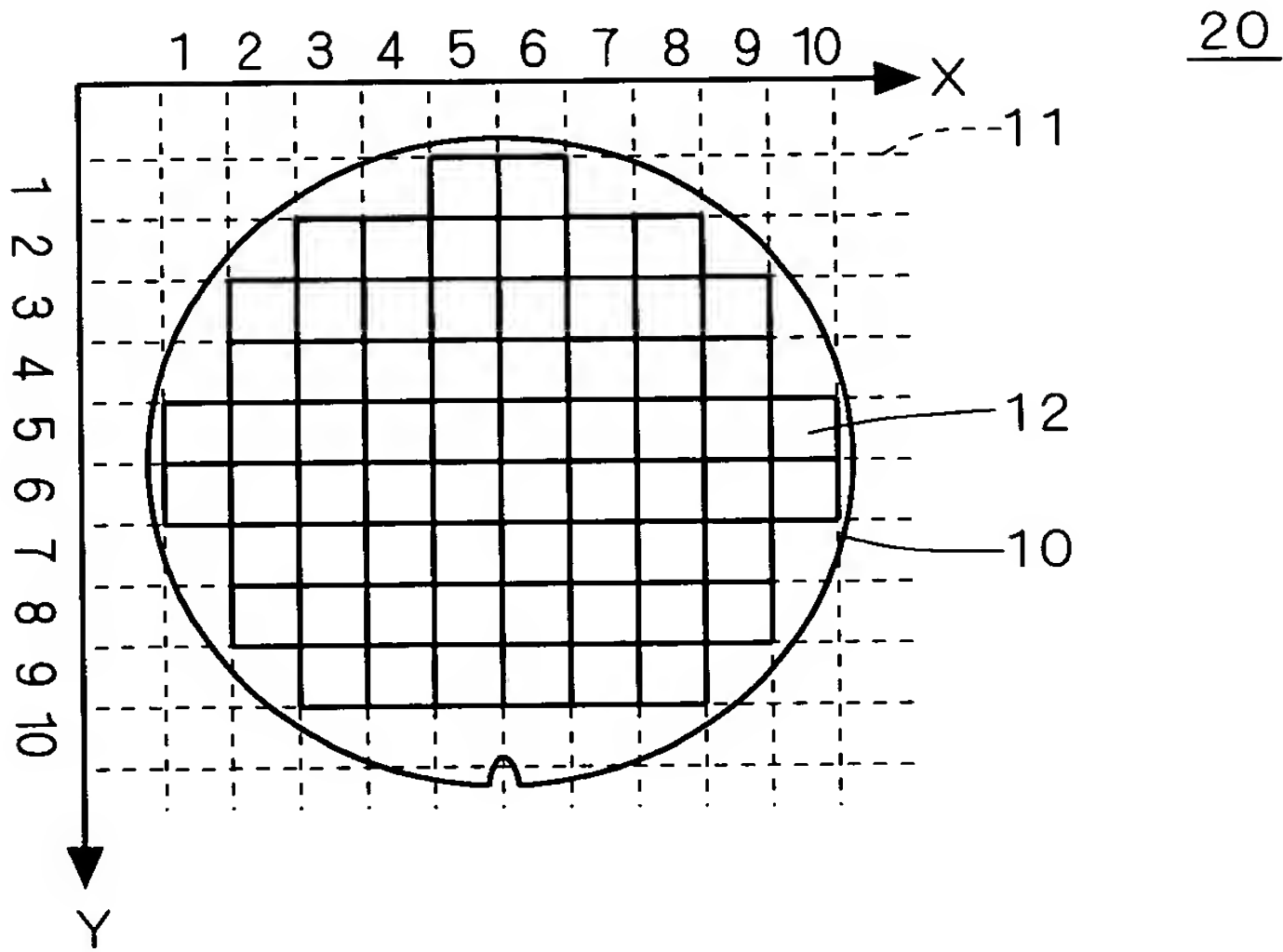


FIG. 4

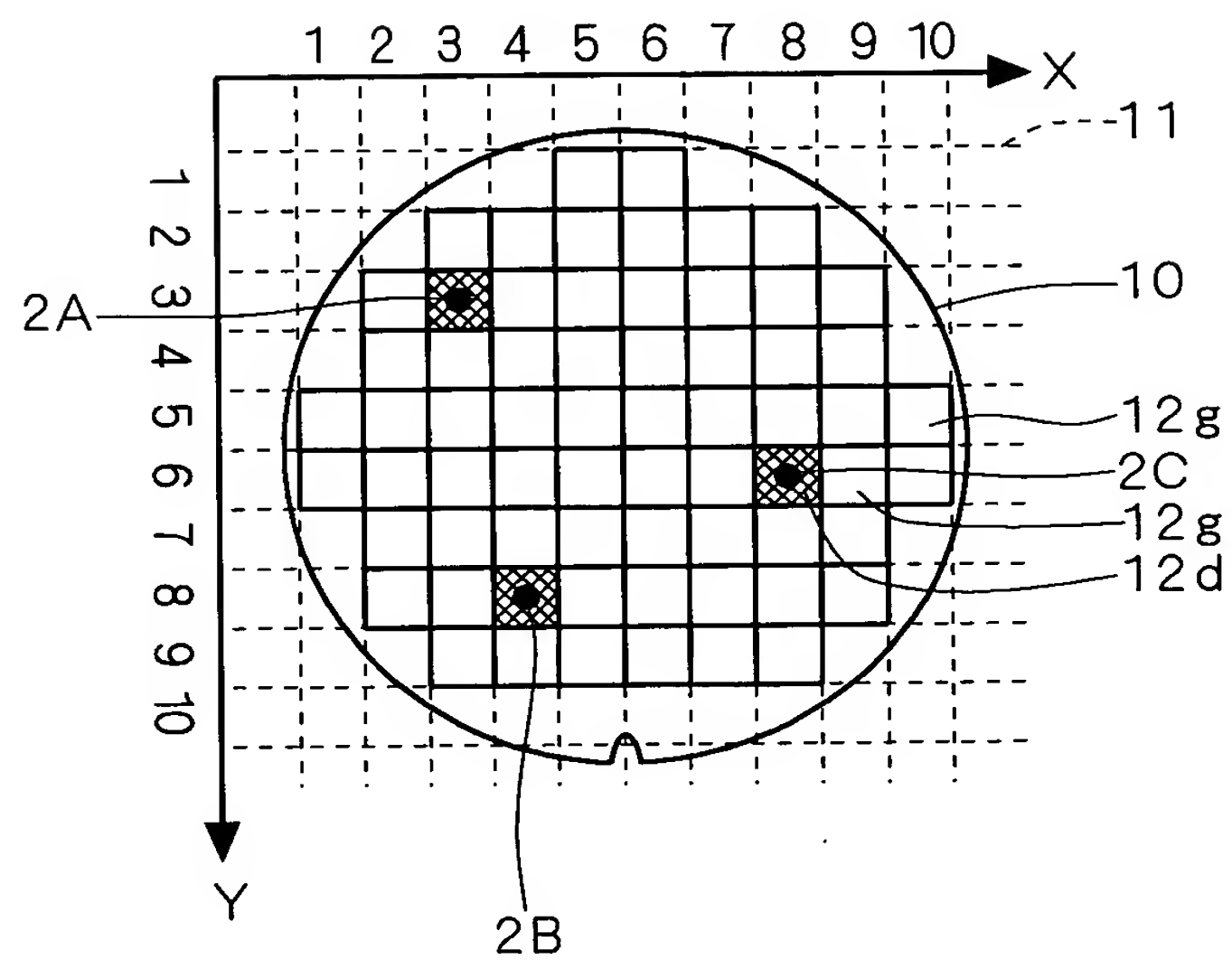


FIG. 5

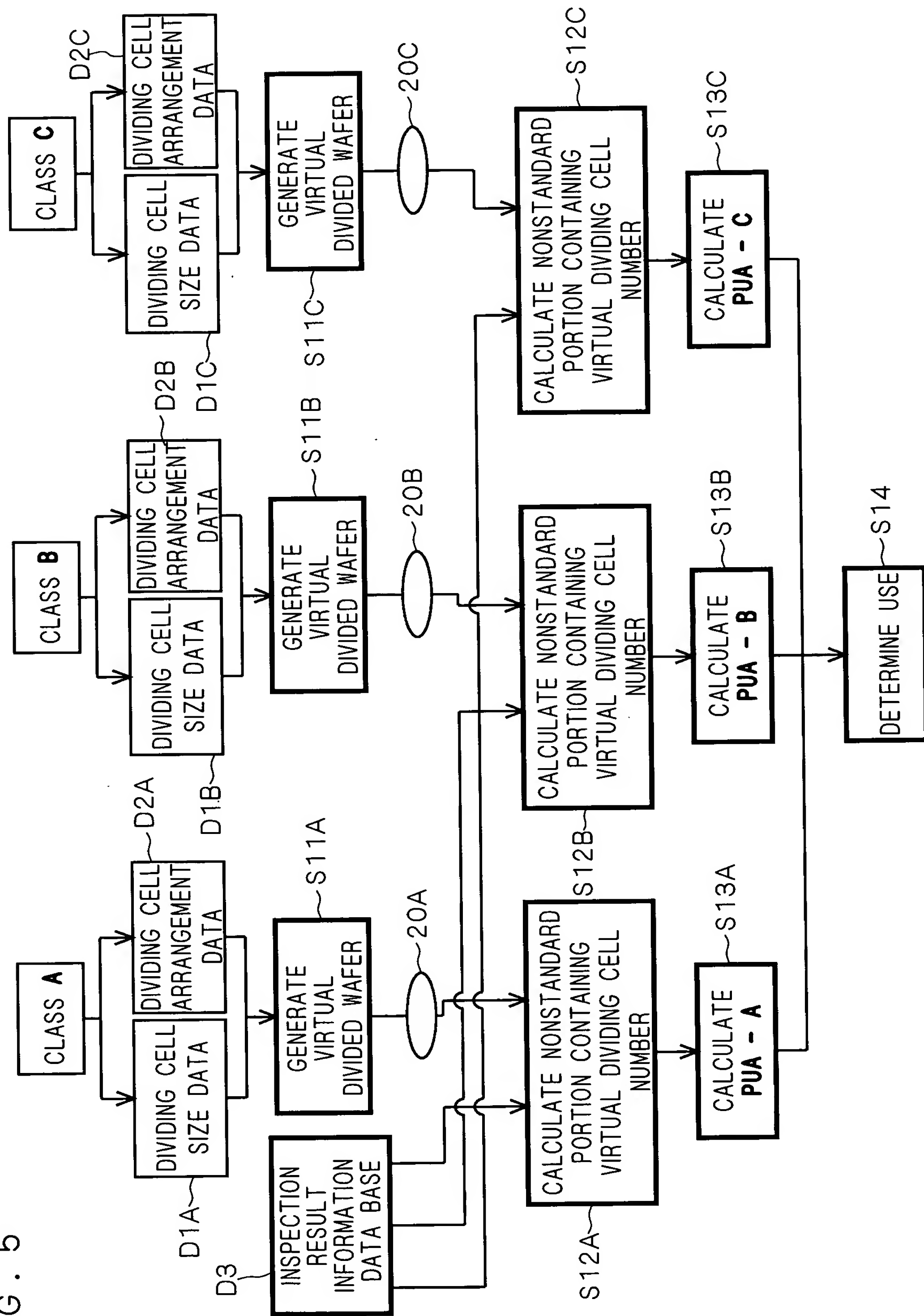


FIG. 6

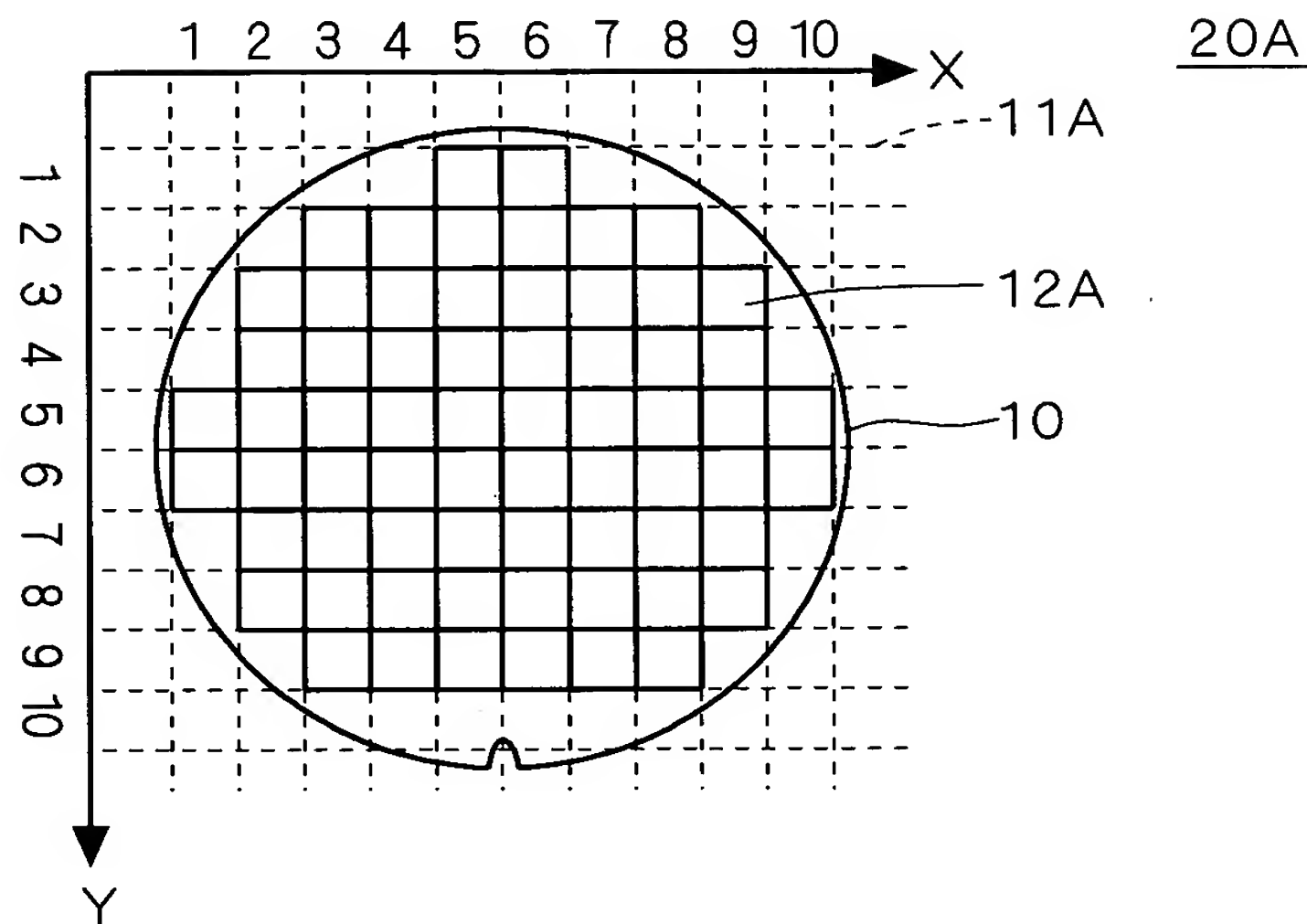


FIG. 7

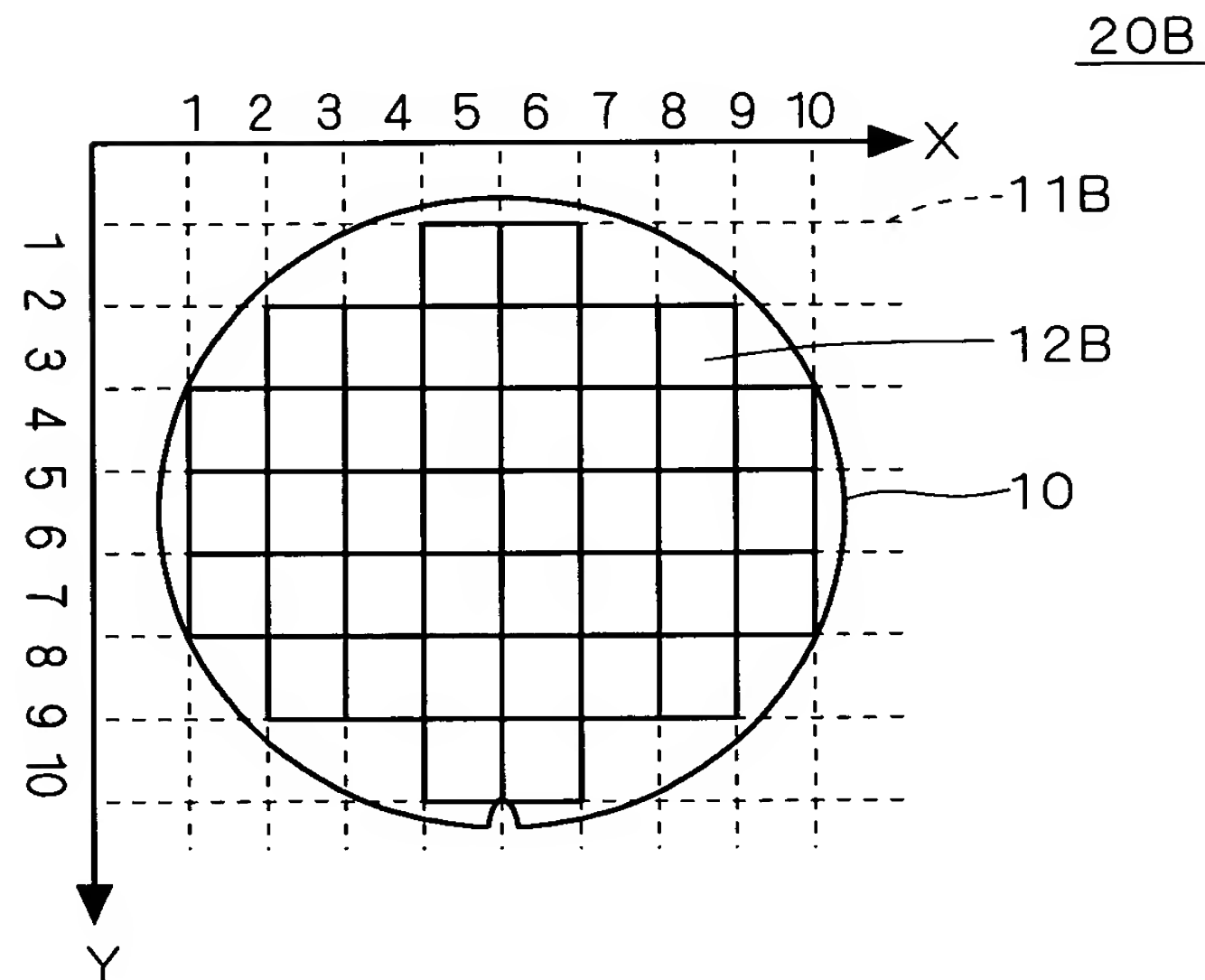


FIG. 8

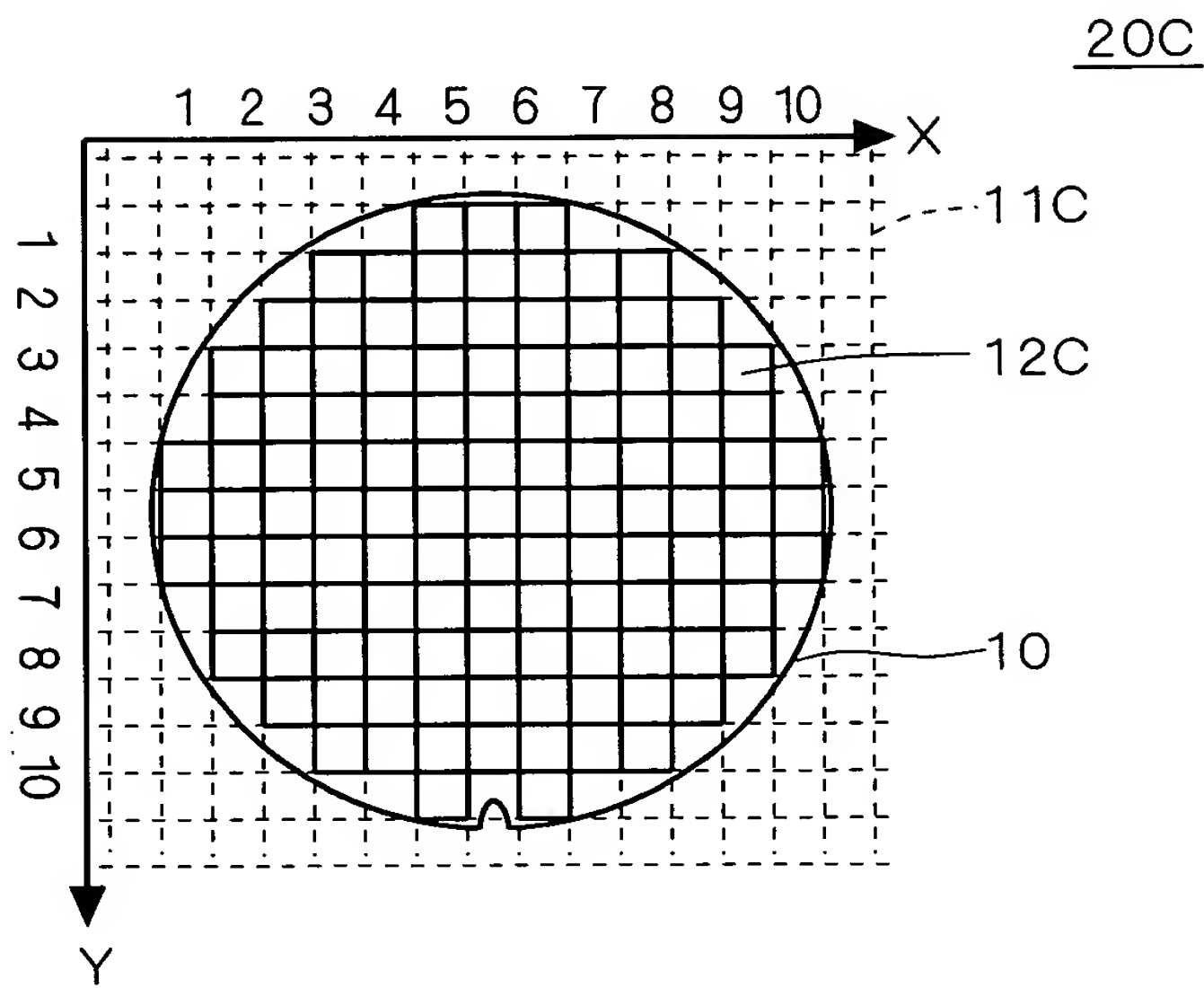


FIG. 9

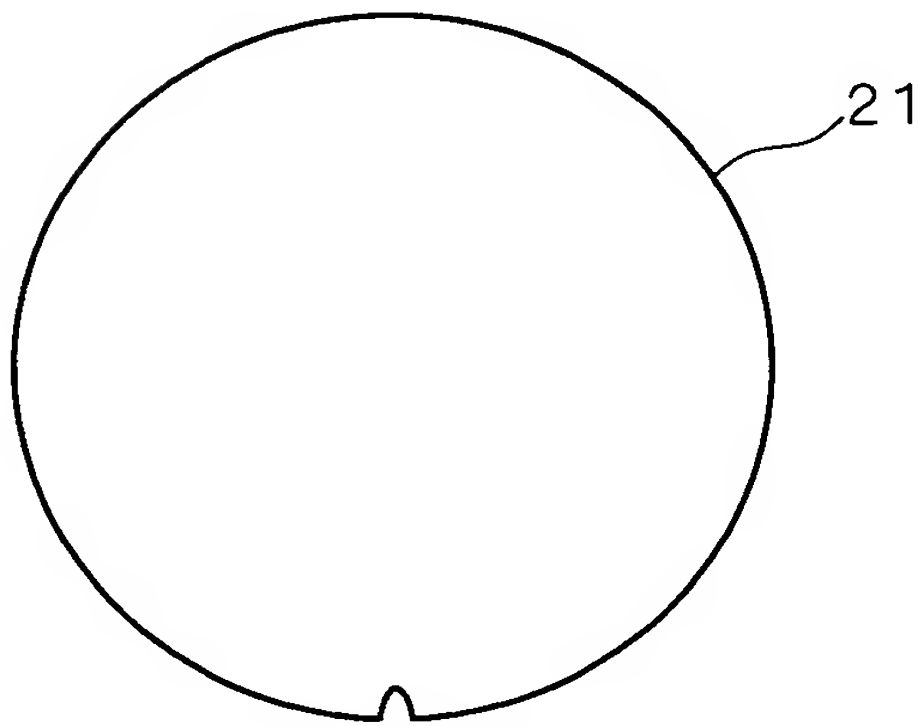


FIG. 10

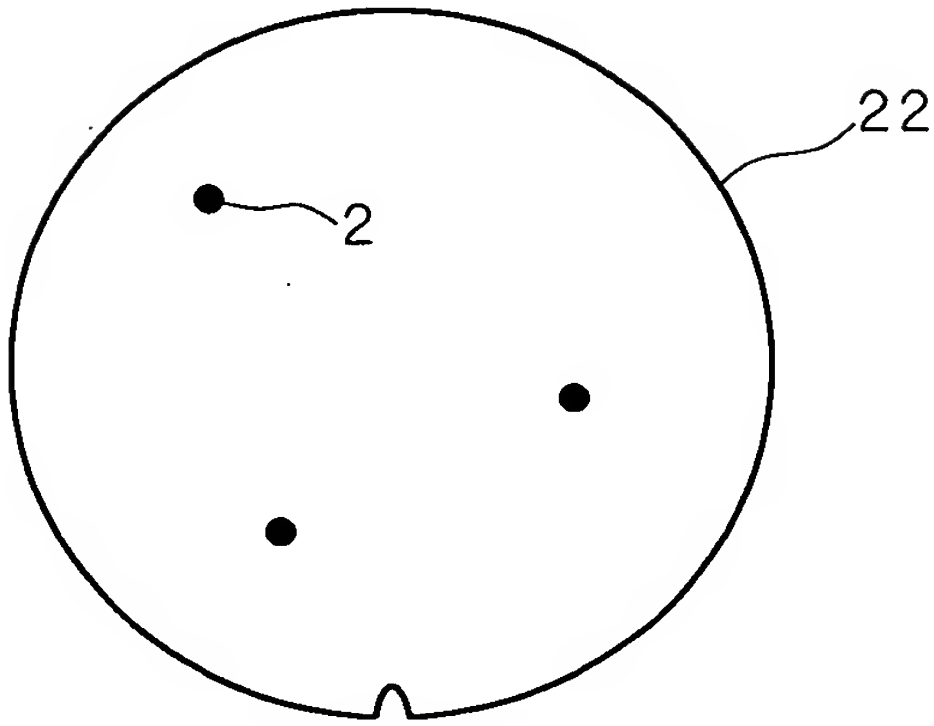


FIG. 11

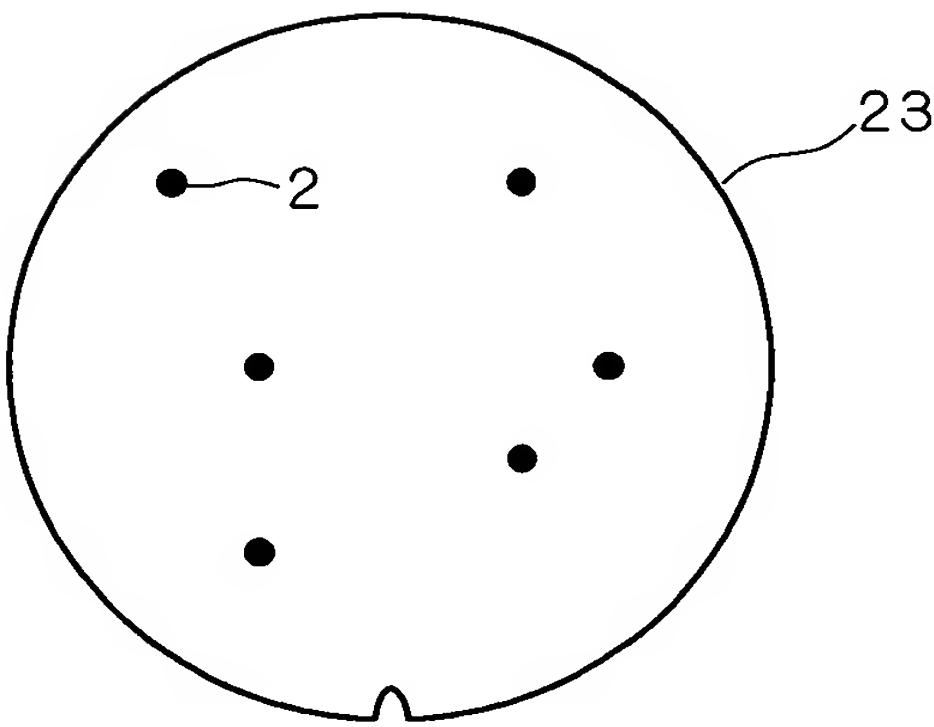


FIG. 12

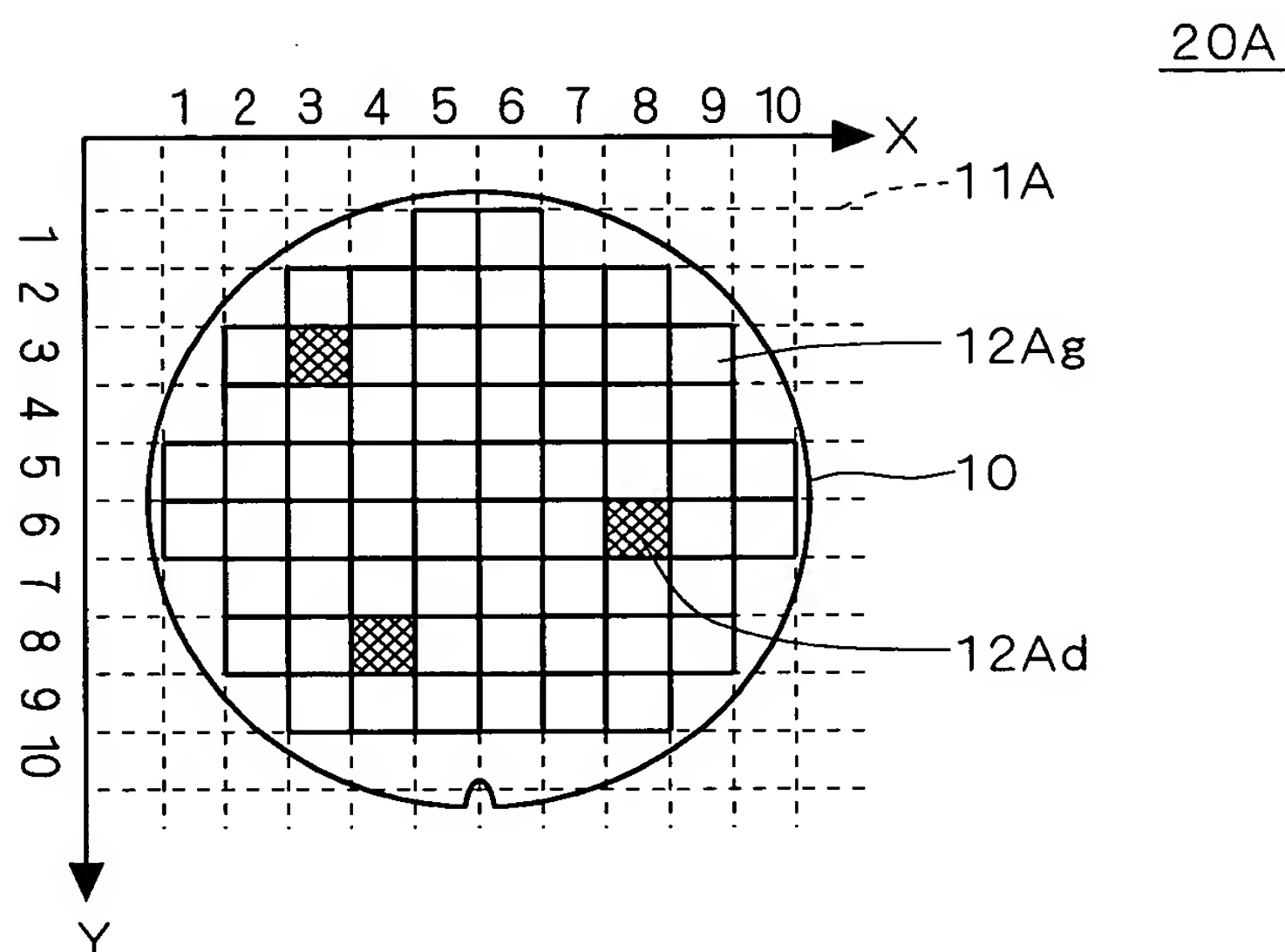


FIG. 13

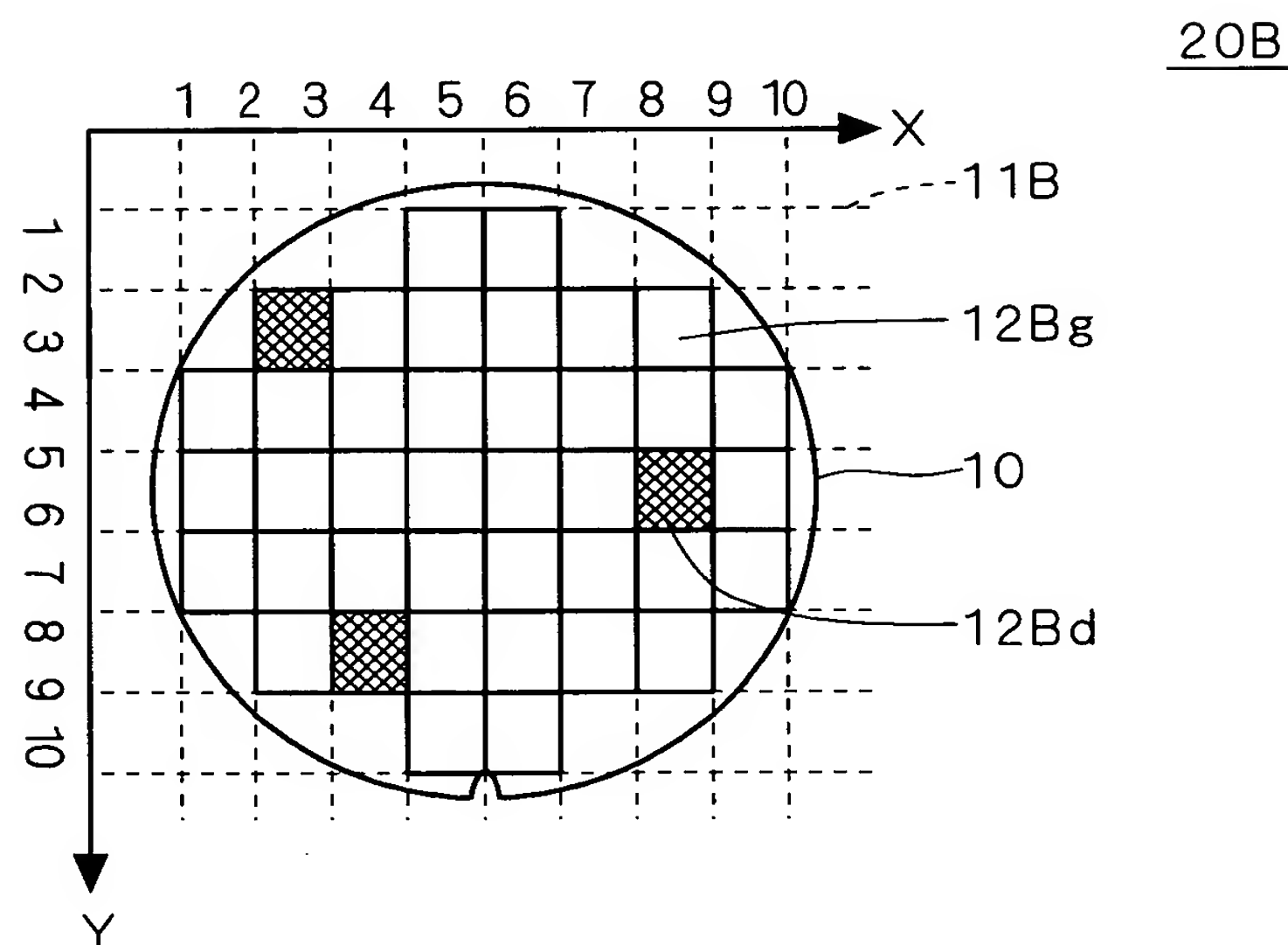


FIG. 14

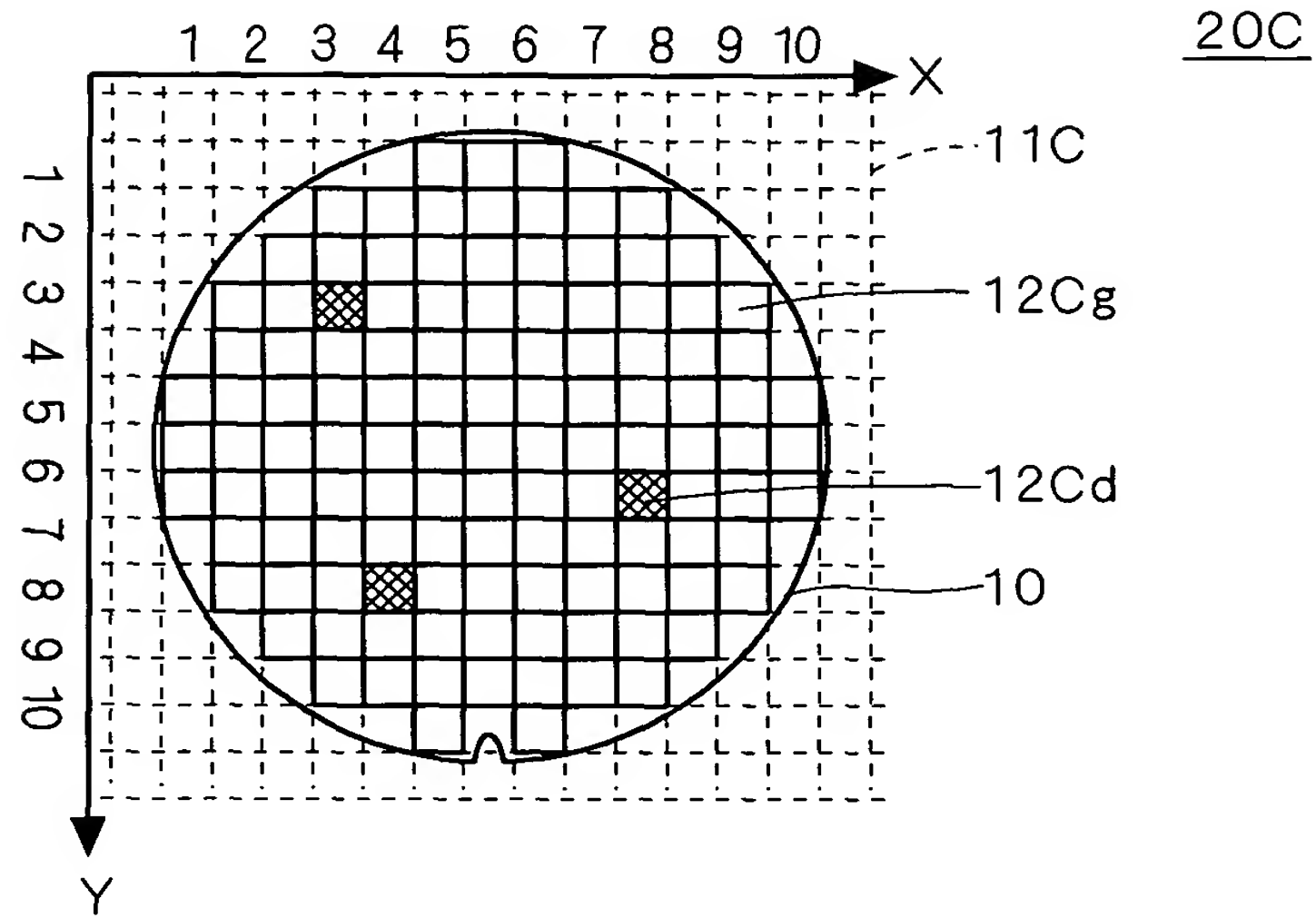


FIG. 15

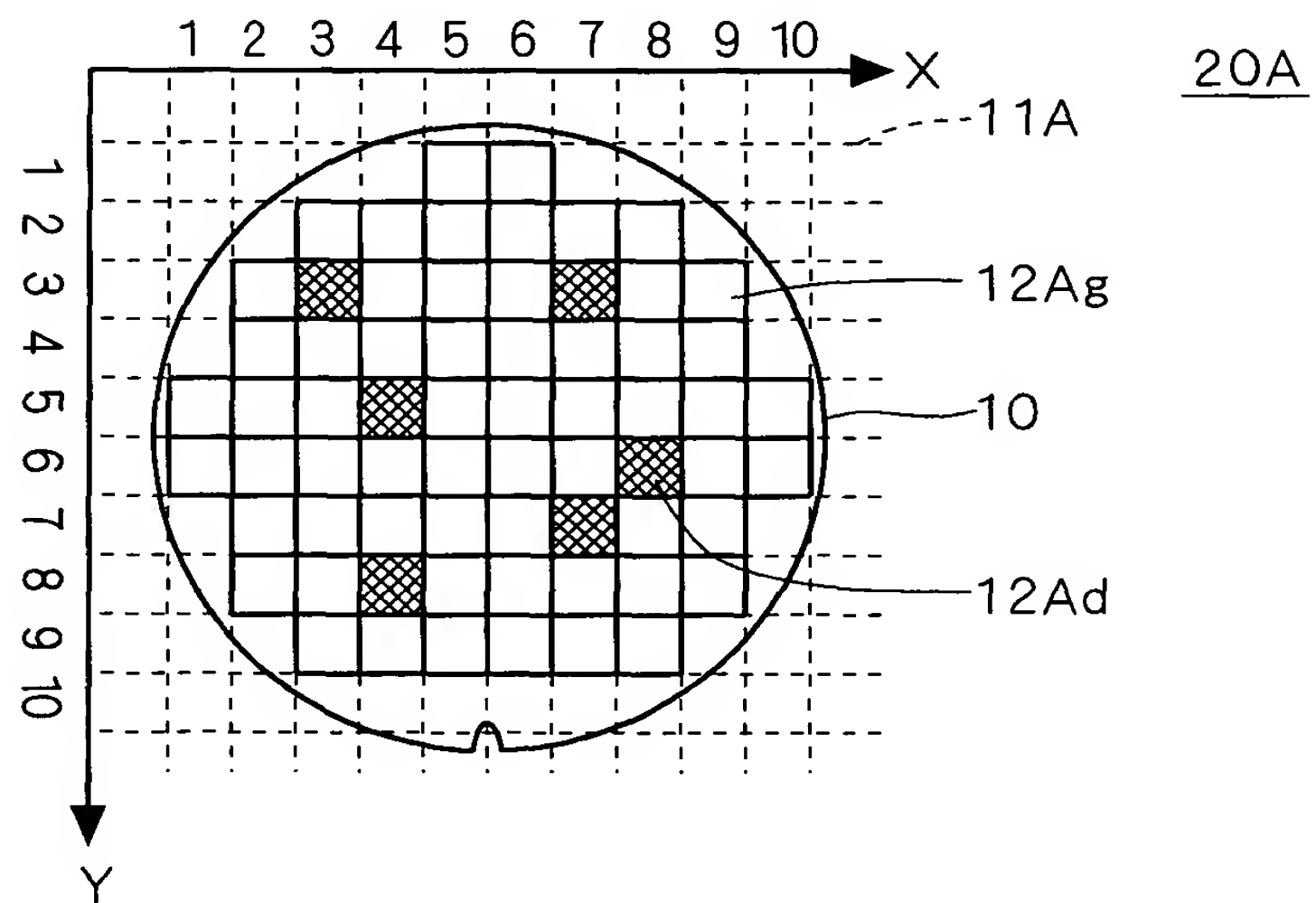


FIG. 16

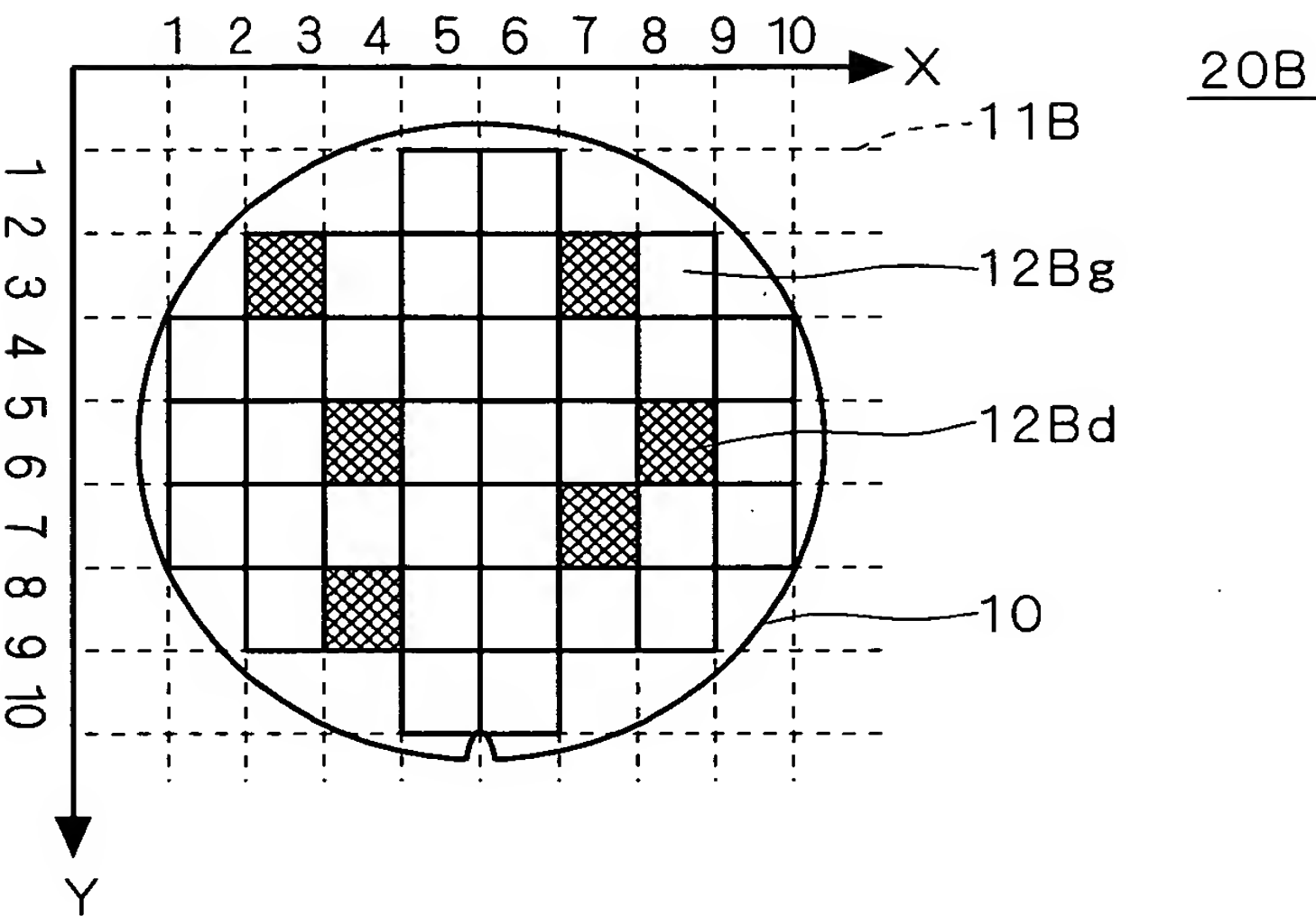


FIG. 17

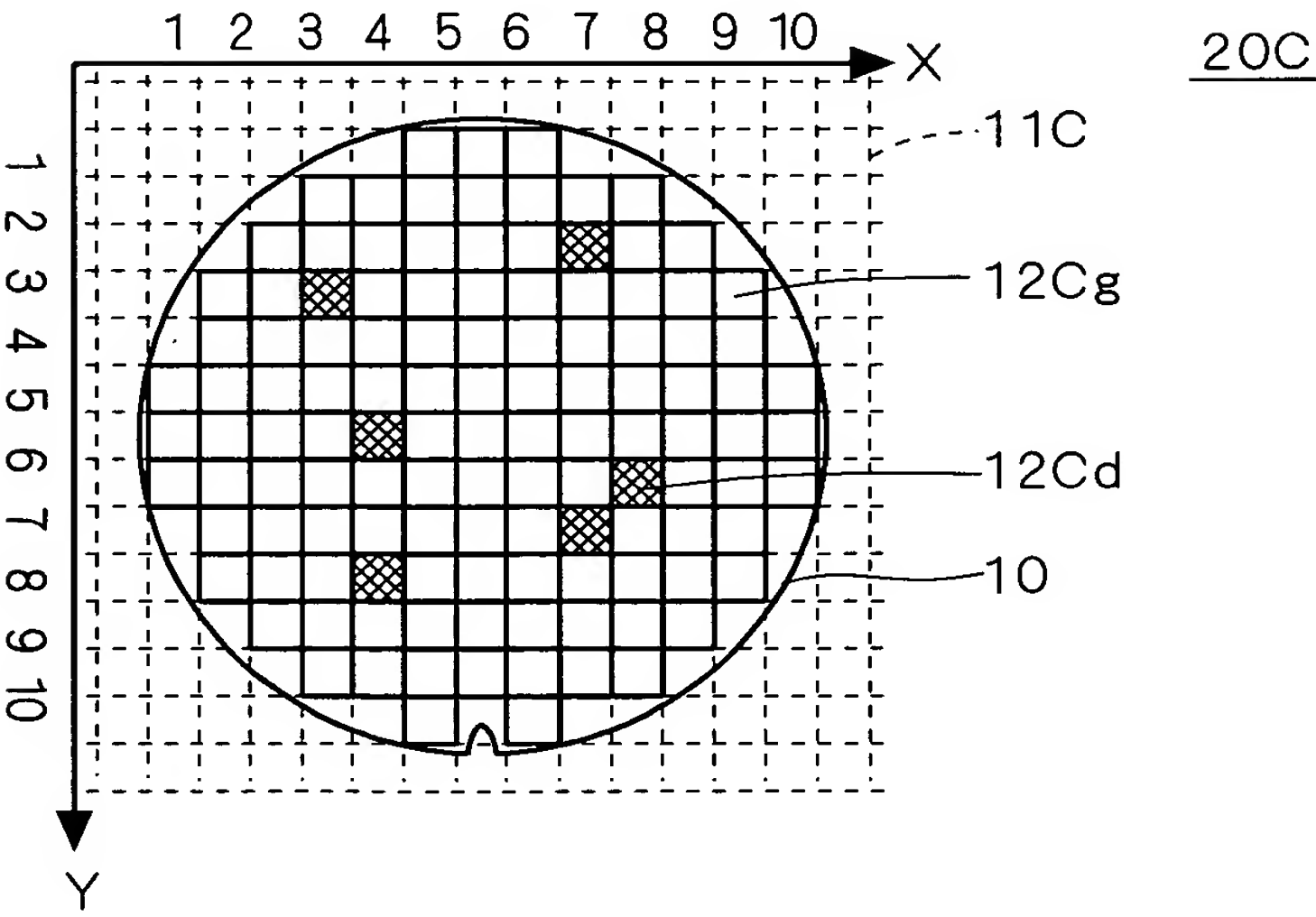


FIG. 18

EMBODIMENT NO.	INSPECTION OBJECT ITEM
3	THICKNESS OF SOI LAYER OF SOI WAFER
4	THICKNESS OF BOX LAYER OF SOI WAFER
5	LOSS OF SOI LAYER OR SOI LAYER AND BOX LAYER IN SOI WAFER
6	HILLOCK - SHAPED DEFECT OF EPITAXIAL WAFER
7	COP

FIG. 19

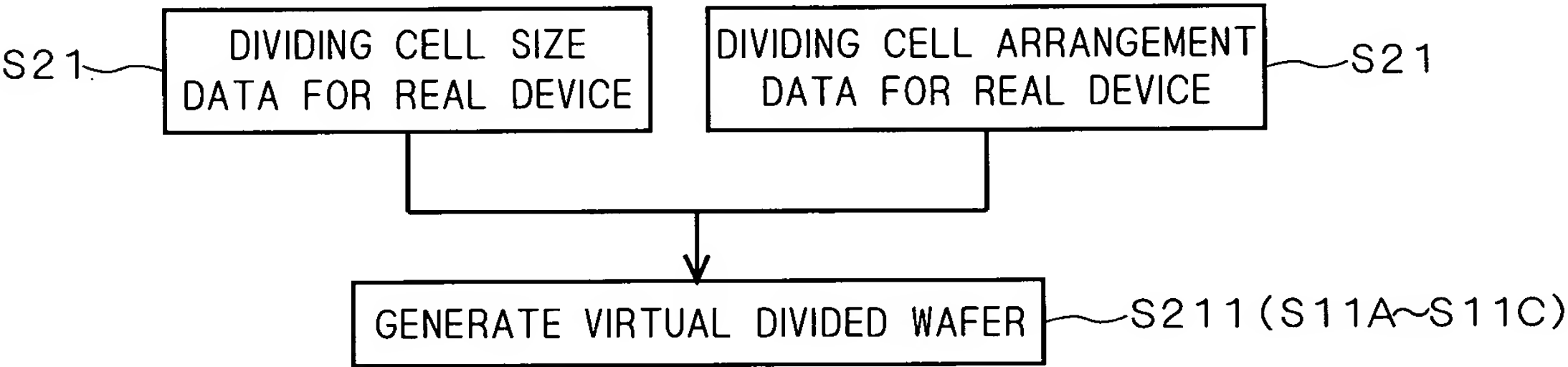


FIG. 20

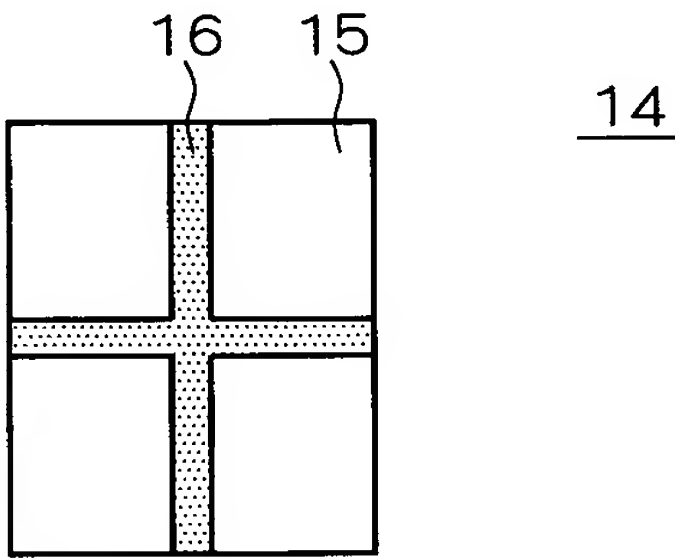


FIG. 21

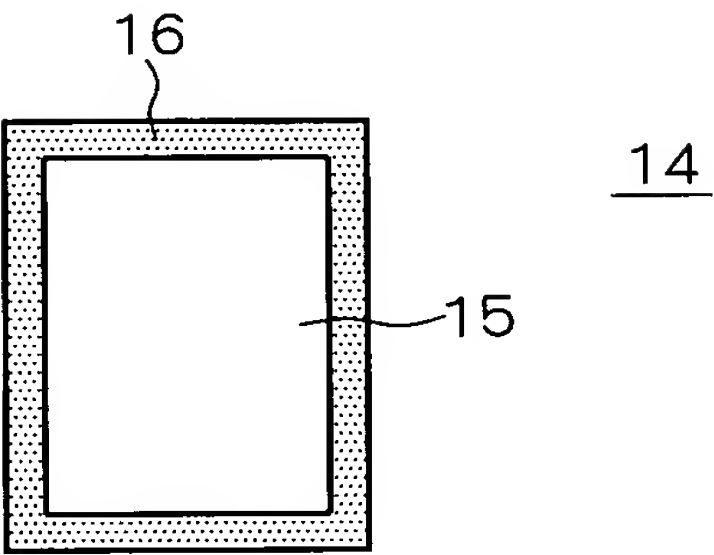


FIG. 22

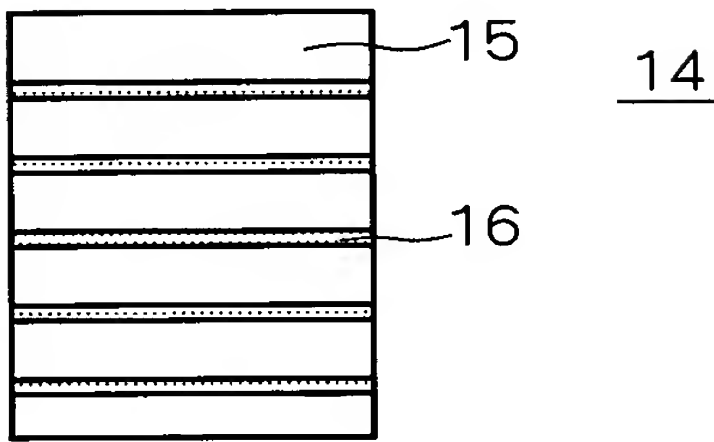


FIG. 23

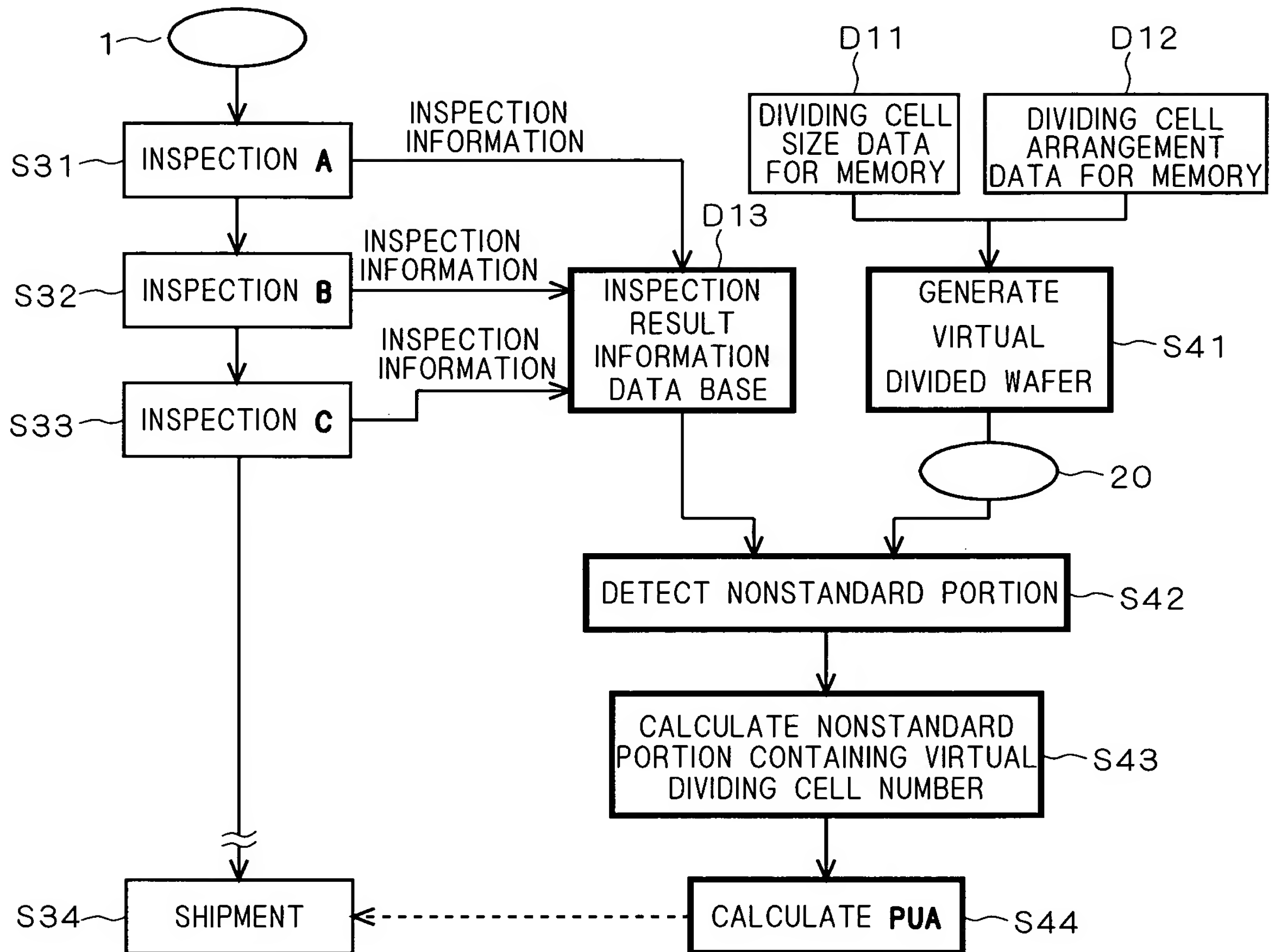


FIG. 24

